US00D430024S

United States Patent [19]

Besemer et al.

[11] **Patent Number: Des. 430,024**

[45] **Date of Patent: ** Aug. 29, 2000**

[54] **CHIP PACKAGING DEVICE**

[75] Inventors: **Donald M. Besemer**, Los Altos Hills; **Virginia W. Goss**, Santa Barbara; **James L. Winkler**, Sunnyvale, all of Calif.

[73] Assignee: **Affymetrix, Inc.**, Santa Clara, Calif.

[**] Term: **14 Years**

[21] Appl. No.: **29/096,089**

[22] Filed: **Nov. 4, 1998**

Related U.S. Application Data

[63] Continuation of application No. 08/485,452, Jun. 7, 1995, Pat. No. 5,945,334.

[51] **LOC (7) Cl.** **09-07**

[52] **U.S. Cl.** **D9/430**

[58] **Field of Search** D9/424, 430, 415, D9/418, 432, 414; D3/201, 264; 206/722, 723, 724, 727, 449, 453, 307; 422/58; 435/283.1; 439/68–73, 330, 331, 525, 526; 248/183.1

[56] **References Cited**

U.S. PATENT DOCUMENTS

D. 358,481	5/1995	Abrams et al.	D3/264
D. 406,759	5/1995	Lawrence	D9/430
4,747,483	5/1988	Grabbe	206/724
4,767,984	8/1988	Bakker	206/724 X
4,954,088	9/1990	Fujizaki et al.	439/73
5,038,248	8/1991	Mwyer	206/724 X
5,109,980	5/1992	Matsuoka et al.	206/724
5,567,177	10/1996	Foerstel et al.	206/724 X
5,839,918	11/1998	Matsuoka	206/724 X

Primary Examiner—Prabhakar Deshmukh
Attorney, Agent, or Firm—Townsend Townsend & Crew; David R. Heckadon

[57] CLAIM

The ornamental design for a chip packaging device, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a chip packaging device showing our new design;

FIG. **2** is a top plan view thereof;

FIG. **3** is a left side elevational view thereof;

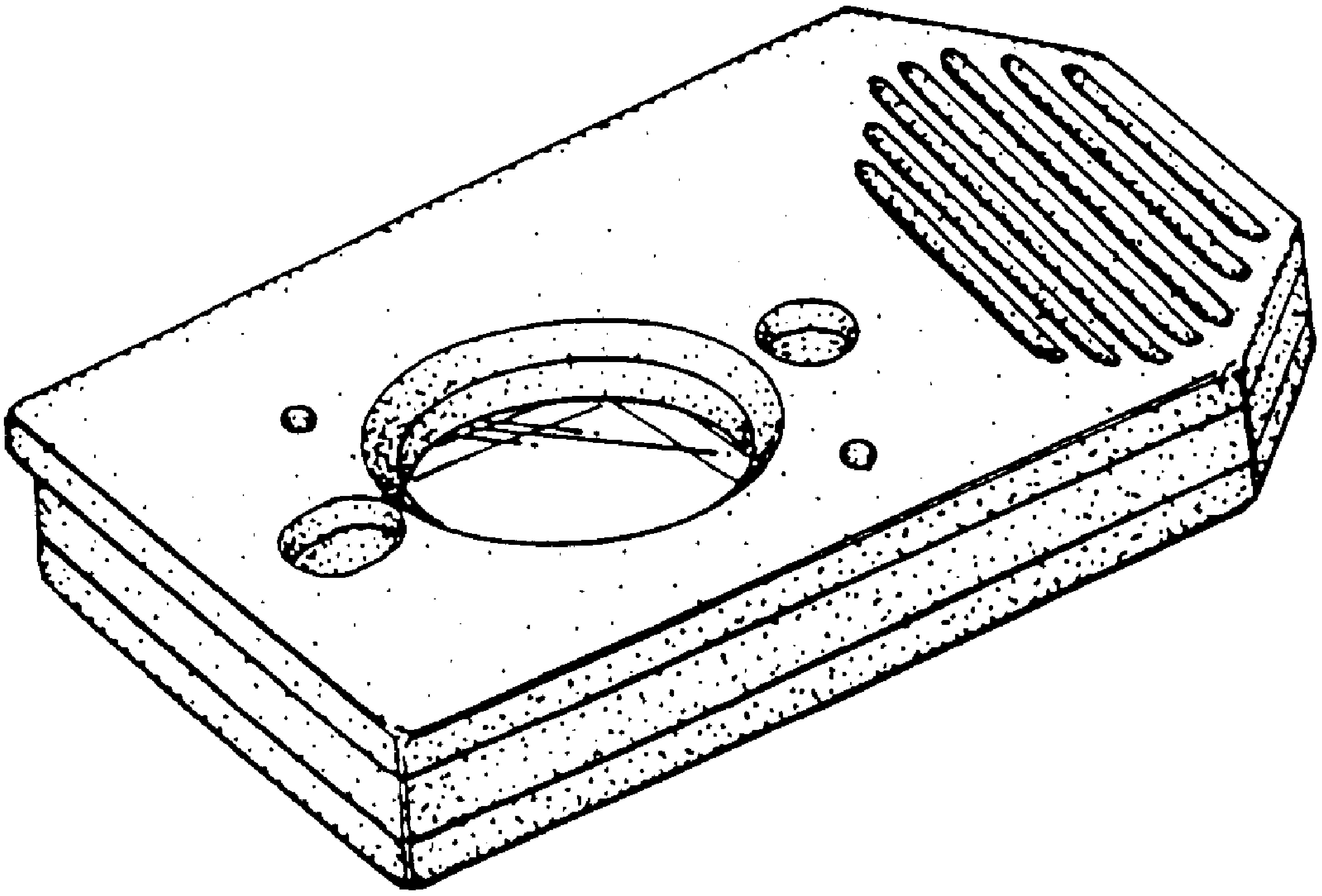
FIG. **4** is a front elevational view, the left side elevational view being a mirror image;

FIG. **5** is a rear elevational view thereof;

FIG. **6** is a right side elevational view thereof; and,

FIG. **7** is a bottom plan view thereof.

1 Claim, 1 Drawing Sheet



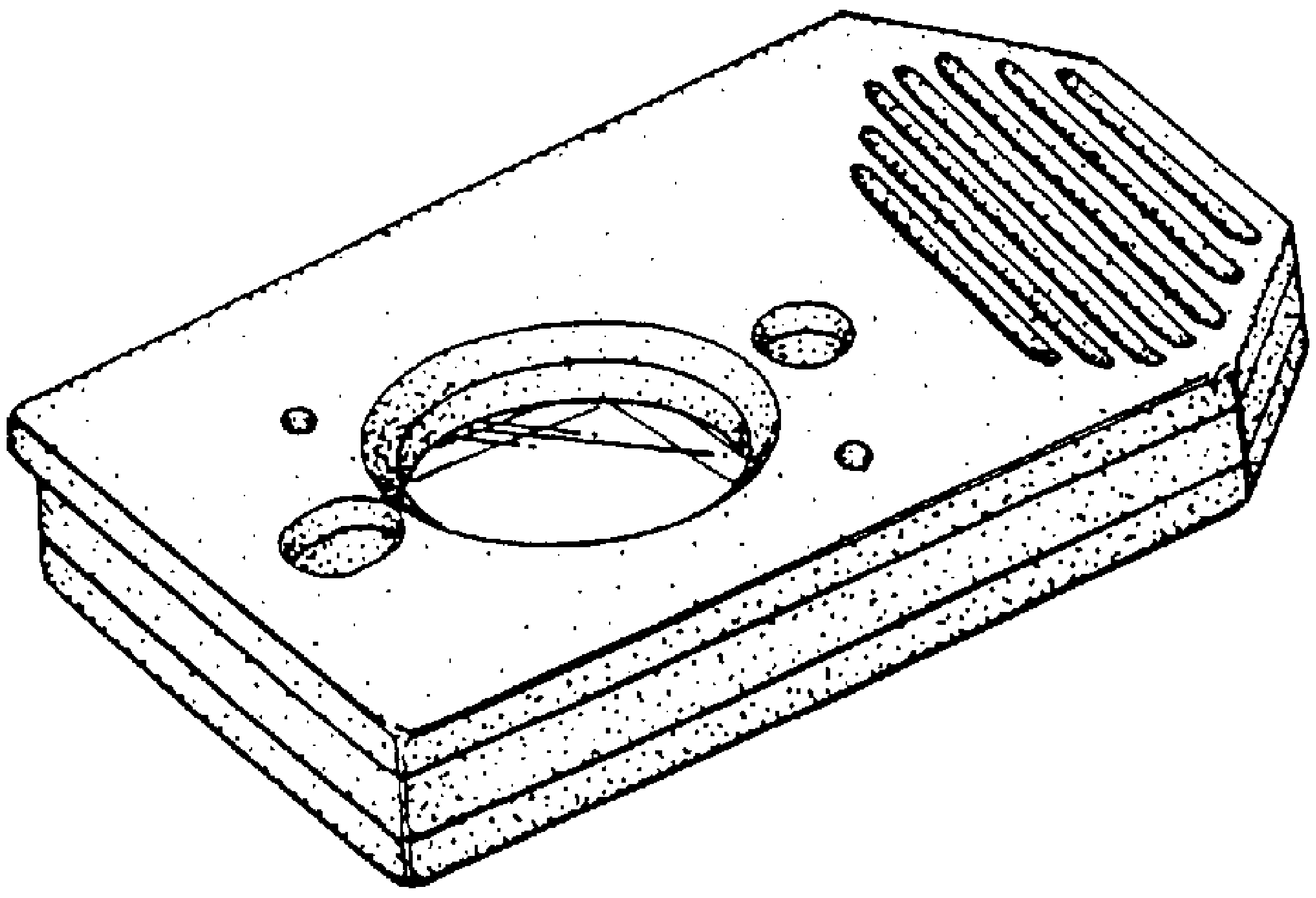


FIG. 1.

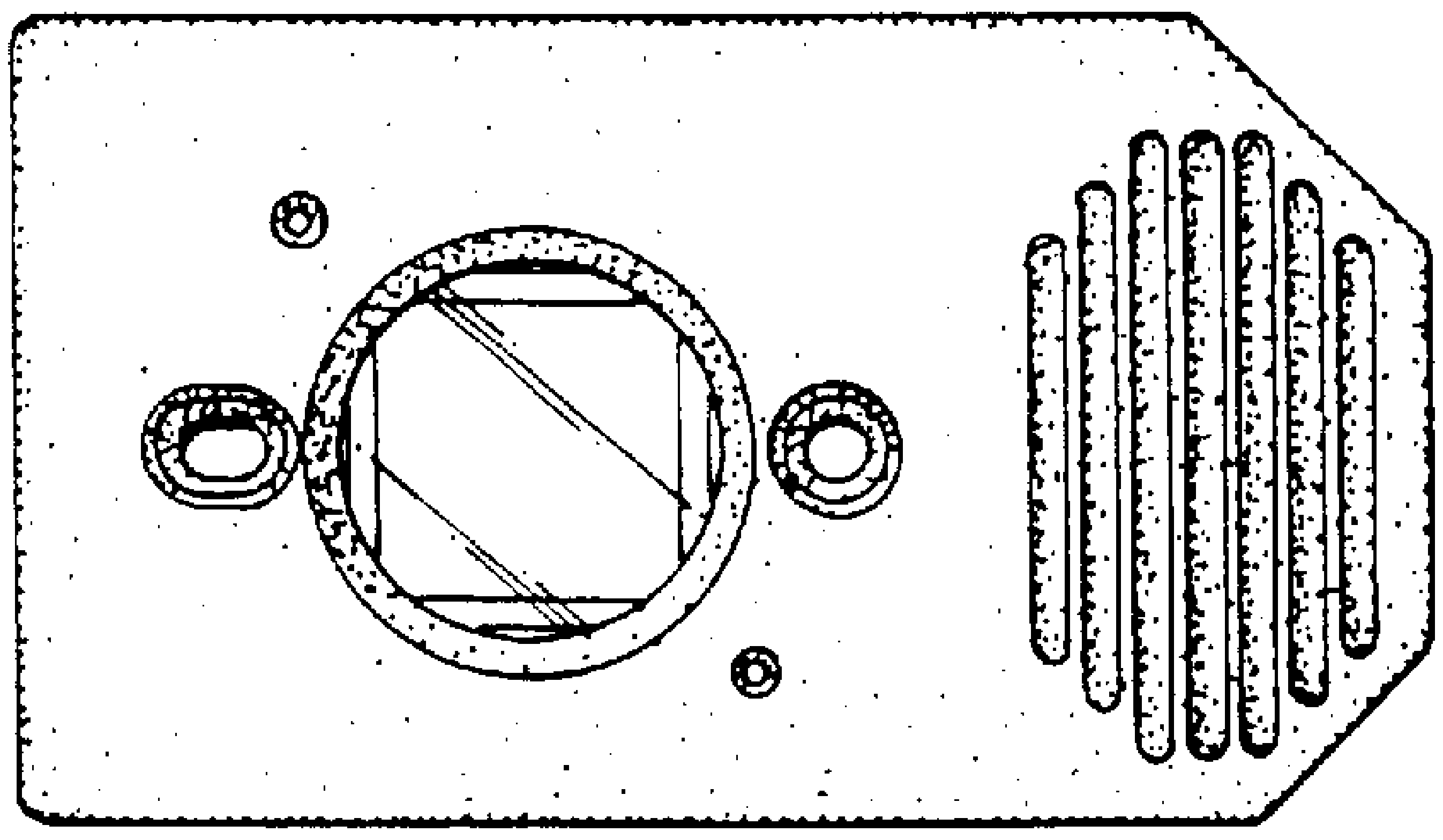


FIG. 2.

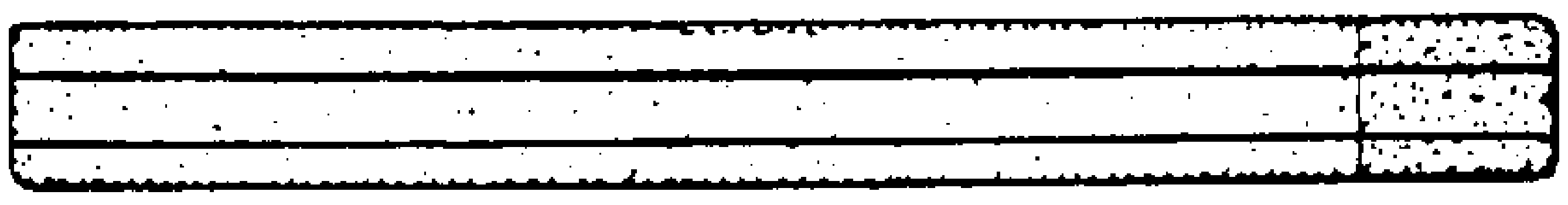


FIG. 3.

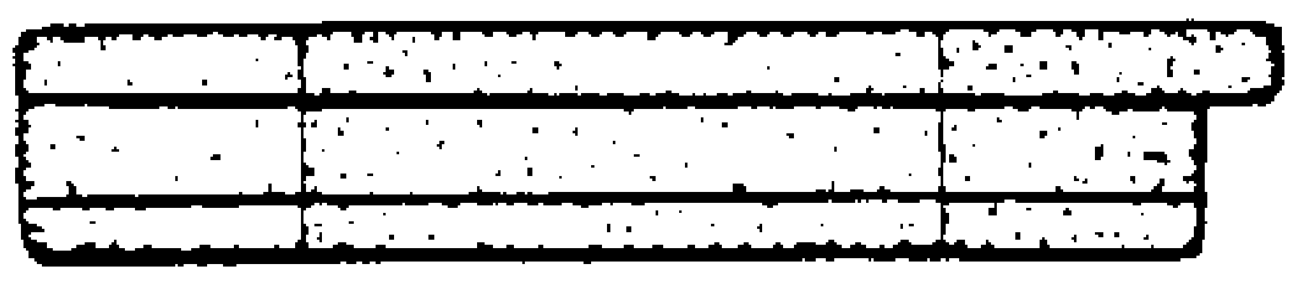


FIG. 4.

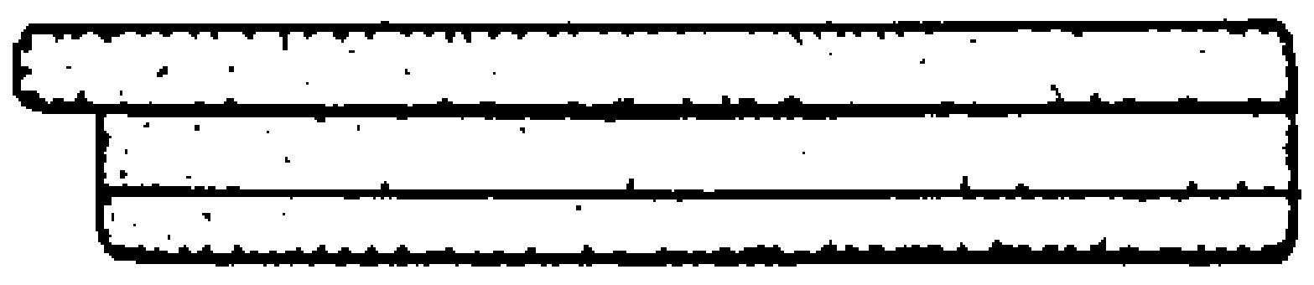


FIG. 5.

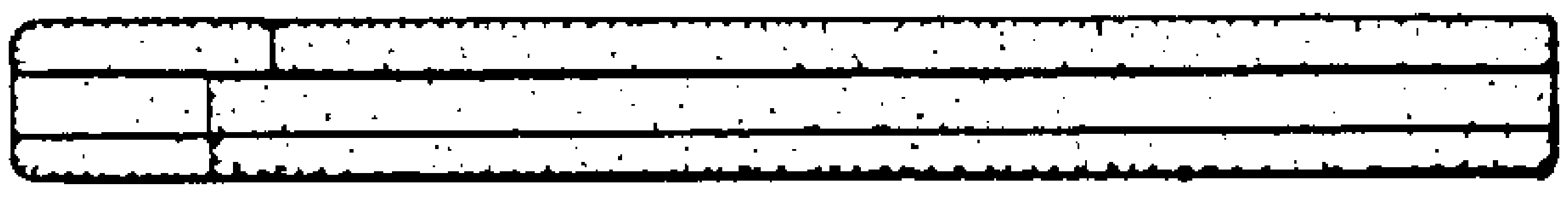


FIG. 6.

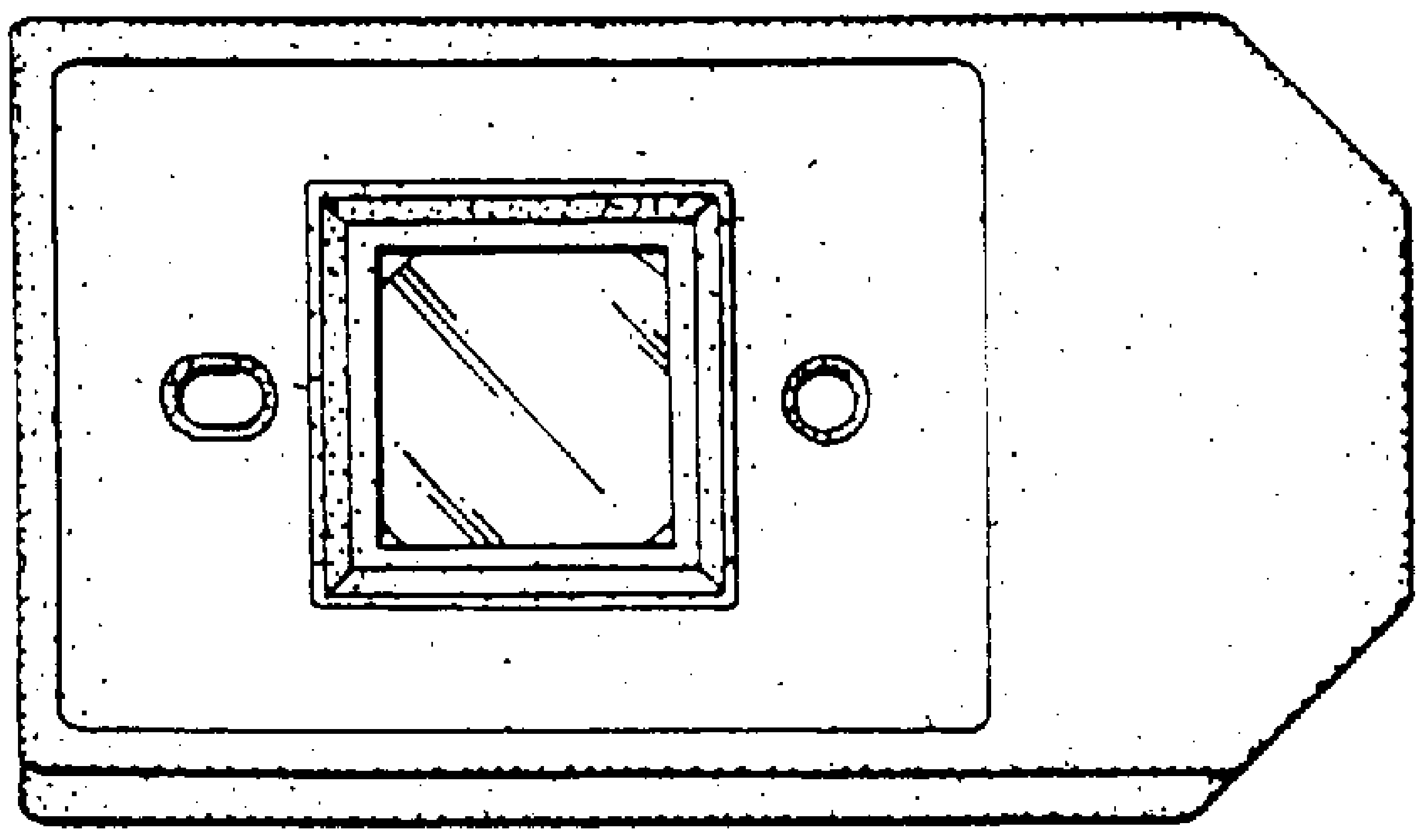


FIG. 7.